update

Refine Search

Search Results -

Terms	Documents
(subsrate) and (remove insulation)	0

Database: US Pre-Grant Publication Full-Text Database; US Patents Full-Text Database; US OCR Full-Text Database; EPO Abstracts Database; JPO Abstracts Database; Derwent World Patents Index; IBM Technical Disclosure Bulletins

Search: L46

Refine Search | Recall Text | Clear | Interrupt

Search History

DATE: Monday, October 04, 2004 Printable Copy Create Case

Set Name side by side	Query	Hit Count	Set Name result set
DB=PGPB,USPT,USOC,EPAB,JPAB,DWPI,TDBD; PLUR=YES; OP=ADJ			
L46	(subsrate) and (remove insulation)	0	L46
L45	L44 and "insulation"	11	L45
L44	(contact thermocouple) and (substrate)	126	L44
DB=PGPB; PLUR=YES; OP=ADJ			
L43	L1 and "substrate"	1	L43
DB=PGPB,USPT,USOC,EPAB,JPAB,DWPI,TDBD; PLUR=YES; OP=ADJ			
L42	L41 and "semiconductor wafer"	23	L42
L41	thin film thermocouple	227	L41
DB=PGPB; PLUR=YES; OP=ADJ			
L40	L1 and "extends"	1	L40
L39	L1 and "extends beyond an edge"	0	L39
DB=PGPB,USPT,USOC,EPAB,JPAB,DWPI,TDBD; PLUR=YES; OP=ADJ			
L38	junction on substrate	0	L38
L37	L20 and "thin film thermocouple"	42	L37

L36	L35 and "thermocouple"	83	L36
L35	measure substrate temperature	149	L35
L34	junction on bare substrate	0	L34
L33	temperature instrumented	12	L33

DB=USPT; PLUR=YES; OP=ADJ

L32	6472240.pn.	1	L32

DB=PGPB,USPT,USOC,EPAB,JPAB,DWPI; PLUR=YES; OP=ADJ

L31	temperature instrumented semiconductor	3	L31

DB=PGPB; PLUR=YES; OP=ADJ

L30	temperature instrumented semiconductor	1	L30

DB=USPT; PLUR=YES; OP=ADJ

L29	L20 and "Laof"	0	L29

DB=PGPB; PLUR=YES; OP=ADJ

L28	L27 and "thermocouple"	3	L28
L27	schuh	132	L27

DB=PGPB,USPT,USOC,EPAB,JPAB,DWPI,TDBD; PLUR=YES; OP=ADJ

L26	temperature indicating wafer	2	L26
L25	temperature calibrating wafer	1	L25
L24	L21 and "SenseArray"	0	L24
L23	L21 and "thermocouple"	224	L23
L22	L21 and "hot junction"	1	L22
L21	L20 and "temperature wafer"	350	L21
L20	374/$	33203	L20
L19	temperature wafer	6691	L19
L18	hot junction formed on substrate	0	L18
L17	L16 and "insulation"	34	L17
L16	forming hot junction	85	L16
L15	L12 and "hot junction"	18	L15
L14	L12 and "hot junction"	18	L14
L13	L12 and "substrate"	13	L13
L12	374/180	149	L12
L11	film extends beyond substrate	2	L11

DB=PGPB; PLUR=YES; OP=ADJ

L10	L1 and "stretch"	0	L10
L9	L1 and "tension"	0	L9
L8	L1 and "compressive"	0	L8
L7	L1 and "compression"	0	L7
L6	L1 and "tensile"	0	L6

DB=PGPB,USPT,USOC,EPAB,JPAB,DWPI,TDBD; PLUR=YES; OP=ADJ

L5	L4 and "thin film"	50	L5
L4	positive strain	803	L4

DB=PGPB; PLUR=YES; OP=ADJ

L3	L2 and "positive"	0	L3
L2	L1 and "0.006"	1	L2
L1	20040101022	1	L1

END OF SEARCH HISTORY